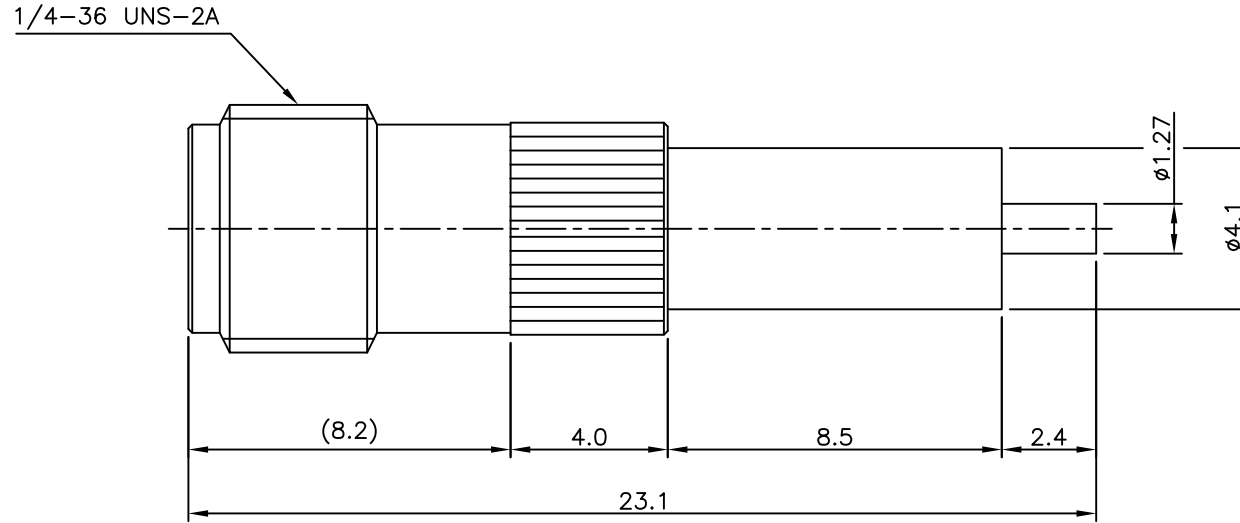


REVISION					
REV	DESCRIPTION		DRAWN	APPR	DATE
IR	Initial Registration		S.Y.EUN	I.C.KIM	2022.07.06.



주 기

1. 재 질 : 표 참조

Description	Material	Plating
Body (Outer Conductor)	SUS	Gold MIL-G-45024
Teflon	PTFE	
PIN	Beryllium Copper	Gold MIL-G-45024

- 성능을 만족하는 동등품 이상일 경우 대체 가능함
- 표기된 모든 치수는 참고 치수임

3	INSULATOR	1	TEFLON		DIN03307-N/1
2	CONTACT	1	BeCu C17300	Gold Plate (1.27 μ m)	DCT04318-5/1
1	BODY	1	SUS	Gold Plate (1.27 μ m)	DBD04843-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2022. 07 . 06.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY	S.H.KIM			
MATERIAL _____	CHECKED BY	TITLE SMA50 SOLDER END JS				
	DRAWN BY					S.Y.EUN
FINISH _____	SCALE 4/1	UNIT mm		A4	DWG NO. CN04061-7/1	
				REVISION	I R	SHEET 1 of 1